

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

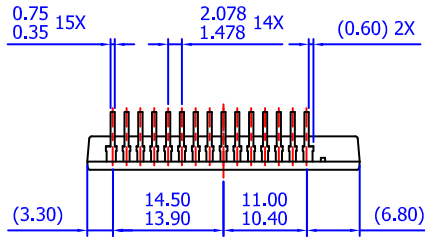


SPMAA-A22 / 22LD, PDD STD, SPM22, CERAMIC, DIP TYPE

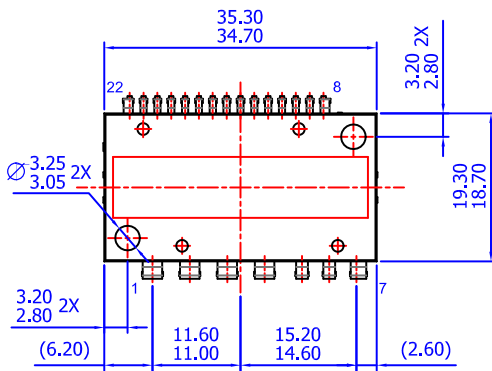
CASE MODEU

ISSUE O

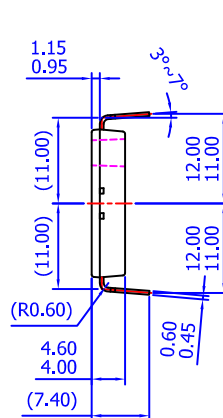
DATE 31 JAN 2017



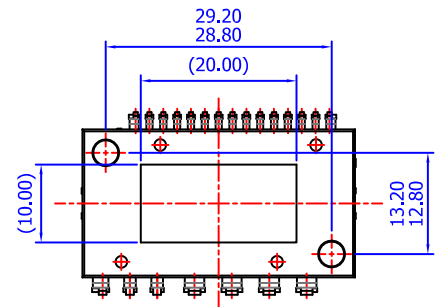
REAR VIEW



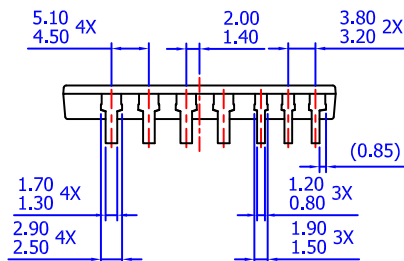
TOP VIEW



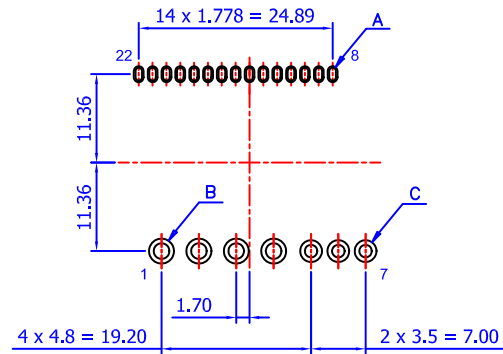
SIDE VIEW



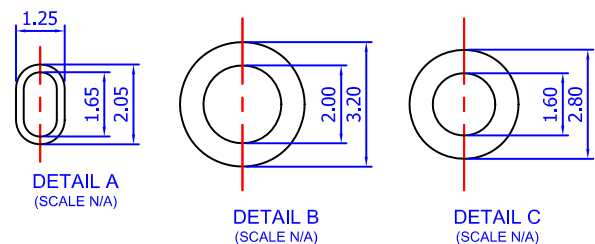
BOTTOM VIEW



FRONT VIEW



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 - B) ALL DIMENSIONS ARE IN MILLIMETERS
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - D) () IS REFERENCE
 - E) [] IS ASS'Y QUALITY



LAND PATTERN RECOMMENDATIONS

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DESCRIPTION:	SPMAA-A22 / 22LD, PDD STD, SPM22, CERAMIC, DIP TYPE	PAGE 1 OF 1

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